&TDK Multilayer Ceramic Chip Capacitors

C2012X7R1A106K125AE



TDK item description C2012X7R1A106KT***S

Applications	Commercial Grade	
Feature	Soft Soft Termination	
Series	C2012 [EIA 0805]	
Status	Production	



	Size
Length(L)	2.00mm +0.45,-0.20mm
Width(W)	1.25mm +0.25,-0.20mm
Thickness(T)	1.25mm +0.25,-0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	10µF ±10%	
Rated Voltage	10VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	10ΜΩ	

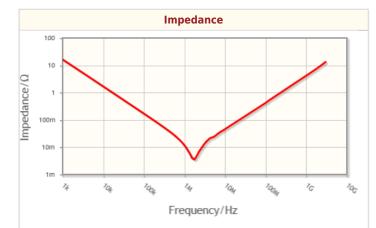
	Other
Coldering Mathed	Wave (Flow)
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

! Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

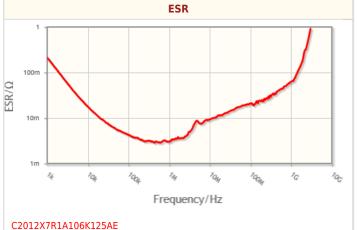
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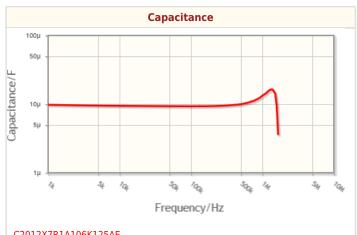


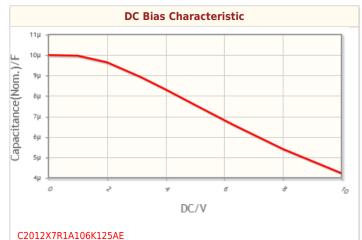


Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

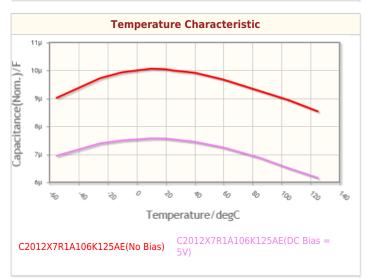


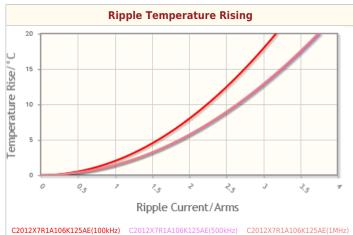
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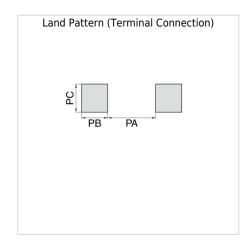
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Associated Images



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